

DS90LV028AQ Automotive LVDS Dual Differential Line Receiver

General Description

The DS90LV028AQ is a dual CMOS differential line receiver designed for applications requiring ultra low power dissipation, low noise and high data rates. The device is designed to support data rates in excess of 400 Mbps (200 MHz) utilizing Low Voltage Differential Signaling (LVDS) technology.

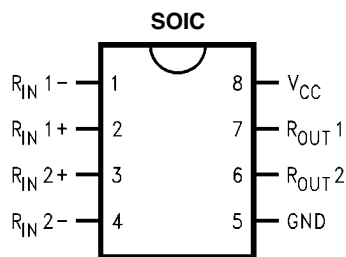
The DS90LV028AQ accepts low voltage (350 mV typical) differential input signals and translates them to 3V CMOS output levels. The DS90LV028AQ has a flow-through design for easy PCB layout.

The DS90LV028AQ and companion LVDS line driver DS90LV027AQ provide a new alternative to high power PECL/ECL devices for high speed point-to-point interface applications.

Features

- AECQ-100 Grade 1
- -40°C to +125°C operating temperature range
- >400 Mbps (200 MHz) switching rates
- 50 ps differential skew (typical)
- 0.1 ns channel-to-channel skew (typical)
- 2.5 ns maximum propagation delay
- 3.3V power supply design
- Flow-through pinout
- Power down high impedance on LVDS inputs
- Low Power design (18mW @ 3.3V static)
- LVDS inputs accept LVDS/CML/LVPECL signals
- Conforms to ANSI/TIA/EIA-644 Standard
- Available in SOIC package

Connection Diagram

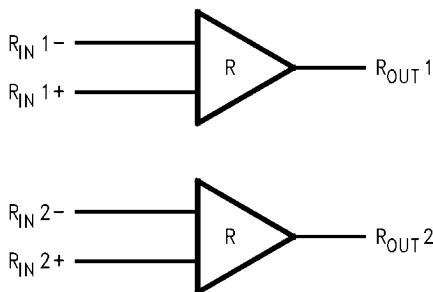


Order Number DS90LV028AQMA
See NS Package Number M08A

Truth Table

INPUTS	OUTPUT
$[R_{IN+}] - [R_{IN-}]$	R_{OUT}
$V_{ID} \geq 0.1V$	H
$V_{ID} \leq -0.1V$	L

Functional Diagram



30064102

Absolute Maximum Ratings (Note 4)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage (V_{CC})	-0.3V to +4V
Input Voltage (R_{IN+} , R_{IN-})	-0.3V to +3.9V
Output Voltage (R_{OUT})	-0.3V to $V_{CC} + 0.3V$
Maximum Package Power Dissipation @ +25°C	
M Package	1068 mW
Derate M Package	9.71 mW/°C above +25°C
Package Thermal Resistance (4-Layer, 2 oz. Cu, JEDEC)	
θ_{JA}	103.0°C/W
θ_{JC}	41.0°C/W
Storage Temperature Range	-65°C to +150°C
Lead Temperature Range Soldering (4 sec.)	+260°C
Maximum Junction Temperature	+135°C

ESD Rating

HBM (Note 1)	≥ 8 kV
MM (Note 2)	≥ 250 V
CDM (Note 3)	≥ 1250 V

Note 1: Human Body Model, applicable std. JESD22-A114C

Note 2: Machine Model, applicable std. JESD22-A115-A

Note 3: Field Induced Charge Device Model, applicable std. JESD22-C101-C

Recommended Operating Conditions

	Min	Typ	Max	Units
Supply Voltage (V_{CC})	+3.0	+3.3	+3.6	V
Receiver Input Voltage	GND		3.0	V
Operating Free Air Temperature (T_A)	-40	25	+125	°C

Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified. (Notes 5, 6)

Symbol	Parameter	Conditions	Pin	Min	Typ	Max	Units
V_{TH}	Differential Input High Threshold	$V_{CM} = +1.2V, 0V, 3V$	R_{IN+}			+100	mV
V_{TL}	Differential Input Low Threshold		R_{IN-}	-100			mV
I_{IN}	Input Current	$V_{IN} = +2.8V$		-10	±1	+10	µA
		$V_{IN} = 0V$		-10	±1	+10	µA
		$V_{IN} = +3.6V$		-20		+20	µA
V_{OH}	Output High Voltage	$I_{OH} = -0.4 mA, V_{ID} = +200 mV$	R_{OUT}	2.7	3.1		V
		$I_{OH} = -0.4 mA, \text{Inputs terminated}$		2.7	3.1		V
		$I_{OH} = -0.4 mA, \text{Inputs shorted}$		2.7	3.1		V
V_{OL}	Output Low Voltage	$I_{OL} = 2 mA, V_{ID} = -200 mV$			0.3	0.5	V
I_{OS}	Output Short Circuit Current	$V_{OUT} = 0V$ (Note 7)		-15	-50	-100	mA
V_{CL}	Input Clamp Voltage	$I_{CL} = -18 mA$		-1.5	-0.8		V
I_{CC}	No Load Supply Current	Inputs Open	V_{CC}		5.4	9	mA

Switching Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified. (Notes 6, 8, 9)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
t_{PHLD}	Differential Propagation Delay High to Low	$C_L = 15 pF$ $V_{ID} = 200 mV$ (Figure 1 and Figure 2)	1.0	1.6	2.5	ns
t_{PLHD}	Differential Propagation Delay Low to High		1.0	1.7	2.5	ns
t_{SKD1}	Differential Pulse Skew $ t_{PHLD} - t_{PLHD} $ (Note 10)		0	50	650	ps
t_{SKD2}	Differential Channel-to-Channel Skew-same device (Note 11)		0	0.1	0.5	ns
t_{SKD3}	Differential Part to Part Skew (Note 12)		0		1.0	ns
t_{SKD4}	Differential Part to Part Skew (Note 13)		0		1.5	ns
t_{TLH}	Rise Time			325	800	ps
t_{THL}	Fall Time			225	800	ps
f_{MAX}	Maximum Operating Frequency (Note 14)			250		MHz

Note 4: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" specifies conditions of device operation.

Note 5: Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground unless otherwise specified (such as V_{ID}).

Note 6: All typicals are given for: $V_{CC} = +3.3V$ and $T_A = +25^\circ C$.

Note 7: Output short circuit current (I_{OS}) is specified as magnitude only, minus sign indicates direction only. Only one output should be shorted at a time, do not exceed maximum junction temperature specification.

Note 8: C_L includes probe and jig capacitance.

Note 9: Generator waveform for all tests unless otherwise specified: $f = 1\text{ MHz}$, $Z_O = 50\Omega$, t_r and t_f (0% to 100%) $\leq 3\text{ ns}$ for R_{IN} .

Note 10: t_{SKD1} is the magnitude difference in differential propagation delay time between the positive-going-edge and the negative-going-edge of the same channel.

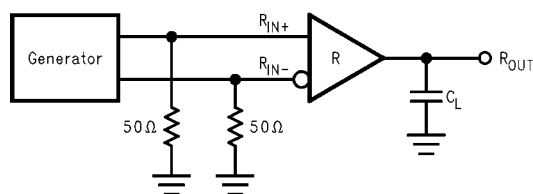
Note 11: t_{SKD2} is the differential channel-to-channel skew of any event on the same device. This specification applies to devices having multiple receivers within the integrated circuit.

Note 12: t_{SKD3} , part to part skew, is the differential channel-to-channel skew of any event between devices. This specification applies to devices at the same V_{CC} and within 5°C of each other within the operating temperature range.

Note 13: t_{SKD4} , part to part skew, is the differential channel-to-channel skew of any event between devices. This specification applies to devices over the recommended operating temperature and voltage ranges, and across process distribution. t_{SKD4} is defined as $I_{Max} - I_{Min}$ differential propagation delay.

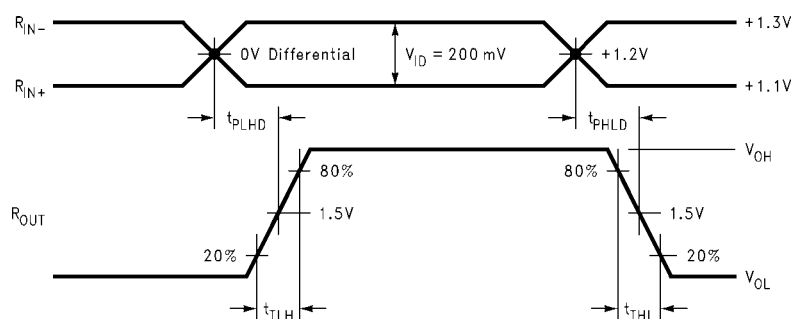
Note 14: f_{MAX} generator input conditions: $t_r = t_f < 1\text{ ns}$ (0% to 100%), 50% duty cycle, differential (1.05V to 1.35 peak to peak). Output criteria: 60%/40% duty cycle, V_{OL} (max 0.4V), V_{OH} (min 2.7V), load = 15 pF (stray plus probes).

Parameter Measurement Information



30064103

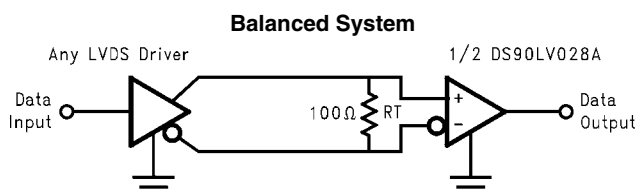
FIGURE 1. Receiver Propagation Delay and Transition Time Test Circuit



30064104

FIGURE 2. Receiver Propagation Delay and Transition Time Waveforms

Typical Application



30064105

FIGURE 3. Point-to-Point Application

Applications Information

General application guidelines and hints for LVDS drivers and receivers may be found in the following application notes: LVDS Owner's Manual (lit #550062-003), AN-808, AN-977, AN-971, AN-916, AN-805, AN-903.

LVDS drivers and receivers are intended to be primarily used in an uncomplicated point-to-point configuration as is shown in *Figure 3*. This configuration provides a clean signaling environment for the fast edge rates of the drivers. The receiver is connected to the driver through a balanced media which may be a standard twisted pair cable, a parallel pair cable, or simply PCB traces. Typically the characteristic impedance of the media is in the range of 100Ω. A termination resistor of 100Ω should be selected to match the media, and is located as close to the receiver input pins as possible. The termination resistor converts the driver output (current mode) into a voltage that is detected by the receiver. Other configurations are possible such as a multi-receiver configuration, but the effects of a mid-stream connector(s), cable stub(s), and other impedance discontinuities as well as ground shifting, noise margin limits, and total termination loading must be taken into account.

The DS90LV028AQ differential line receiver is capable of detecting signals as low as 100 mV, over a ±1V common-mode range centered around +1.2V. This is related to the driver offset voltage which is typically +1.2V. The driven signal is centered around this voltage and may shift ±1V around this center point. The ±1V shifting may be the result of a ground potential difference between the driver's ground reference and the receiver's ground reference, the common-mode effects of coupled noise, or a combination of the two. The AC parameters of both receiver input pins are optimized for a recommended operating input voltage range of 0V to +2.4V (measured from each pin to ground). The device will operate for receiver input voltages up to V_{CC} , but exceeding V_{CC} will turn on the ESD protection circuitry which will clamp the bus voltages.

POWER DECOUPLING RECOMMENDATIONS

Bypass capacitors must be used on power pins. Use high frequency ceramic (surface mount is recommended) 0.1μF and 0.01μF capacitors in parallel at the power supply pin with the smallest value capacitor closest to the device supply pin. Additional scattered capacitors over the printed circuit board will improve decoupling. Multiple vias should be used to connect the decoupling capacitors to the power planes. A 10μF (35V) or greater solid tantalum capacitor should be connected at the power entry point on the printed circuit board between the supply and ground.

PC BOARD CONSIDERATIONS

Use at least 4 PCB board layers (top to bottom): LVDS signals, ground, power, TTL signals.

Isolate TTL signals from LVDS signals, otherwise the TTL signals may couple onto the LVDS lines. It is best to put TTL and LVDS signals on different layers which are isolated by a power/ground plane(s).

Keep drivers and receivers as close to the (LVDS port side) connectors as possible.

DIFFERENTIAL TRACES

Use controlled impedance traces which match the differential impedance of your transmission medium (ie. cable) and termination resistor. Run the differential pair trace lines as close together as possible as soon as they leave the IC (stubs should be < 10mm long). This will help eliminate reflections

and ensure noise is coupled as common-mode. In fact, we have seen that differential signals which are 1mm apart radiate far less noise than traces 3mm apart since magnetic field cancellation is much better with the closer traces. In addition, noise induced on the differential lines is much more likely to appear as common-mode which is rejected by the receiver.

Match electrical lengths between traces to reduce skew. Skew between the signals of a pair means a phase difference between signals which destroys the magnetic field cancellation benefits of differential signals and EMI will result! (Note that the velocity of propagation, $v = c/E$, where c (the speed of light) = 0.2997mm/ps or 0.0118 in/ps). Do not rely solely on the autoroute function for differential traces. Carefully review dimensions to match differential impedance and provide isolation for the differential lines. Minimize the number of vias and other discontinuities on the line.

Avoid 90° turns (these cause impedance discontinuities). Use arcs or 45° bevels.

Within a pair of traces, the distance between the two traces should be minimized to maintain common-mode rejection of the receivers. On the printed circuit board, this distance should remain constant to avoid discontinuities in differential impedance. Minor violations at connection points are allowable.

TERMINATION

Use a termination resistor which best matches the differential impedance or your transmission line. The resistor should be between 90Ω and 130Ω. Remember that the current mode outputs need the termination resistor to generate the differential voltage. LVDS will not work correctly without resistor termination. Typically, connecting a single resistor across the pair at the receiver end will suffice.

Surface mount 1% - 2% resistors are the best. PCB stubs, component lead, and the distance from the termination to the receiver inputs should be minimized. The distance between the termination resistor and the receiver should be < 10mm (12mm MAX).

INPUT FAILSAFE BIASING

External pull up and pull down resistors may be used to provide enough of an offset to enable an input failsafe under open-circuit conditions. This configuration ties the positive LVDS input pin to VDD thru a pull up resistor and the negative LVDS input pin is tied to GND by a pull down resistor. The pull up and pull down resistors should be in the 5kΩ to 15kΩ range to minimize loading and waveform distortion to the driver. The common-mode bias point ideally should be set to approximately 1.2V (less than 1.75V) to be compatible with the internal circuitry. Please refer to application note AN-1194, "Failsafe Biasing of LVDS Interfaces" for more information.

PROBING LVDS TRANSMISSION LINES

Always use high impedance (> 100kΩ), low capacitance (< 2 pF) scope probes with a wide bandwidth (1 GHz) scope. Improper probing will give deceiving results.

CABLES AND CONNECTORS, GENERAL COMMENTS

When choosing cable and connectors for LVDS it is important to remember:

Use controlled impedance media. The cables and connectors you use should have a matched differential impedance of about 100Ω. They should not introduce major impedance discontinuities.

Balanced cables (e.g. twisted pair) are usually better than unbalanced cables (ribbon cable, simple coax) for noise re-

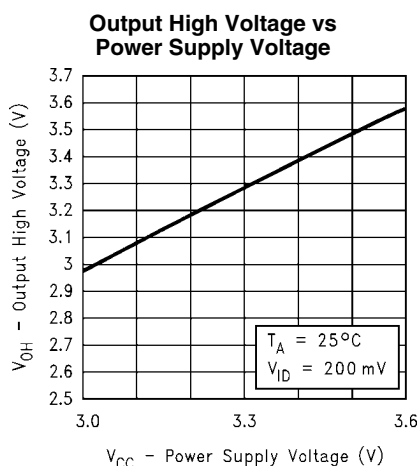
duction and signal quality. Balanced cables tend to generate less EMI due to field canceling effects and also tend to pick up electromagnetic radiation a common-mode (not differential mode) noise which is rejected by the receiver.

For cable distances $< 0.5\text{M}$, most cables can be made to work effectively. For distances $0.5\text{M} \leq d \leq 10\text{M}$, CAT 3 (category 3) twisted pair cable works well, is readily available and relatively inexpensive.

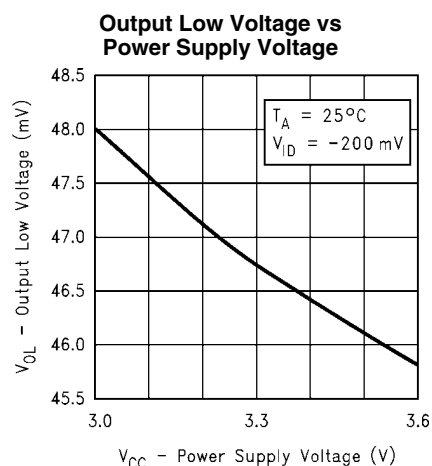
Pin Descriptions

Pin No.	Name	Description
1, 4	R_{IN-}	Inverting receiver input pin
2, 3	R_{IN+}	Non-inverting receiver input pin
6, 7	R_{OUT}	Receiver output pin
8	V_{CC}	Power supply pin, $+3.3\text{V} \pm 0.3\text{V}$
5	GND	Ground pin

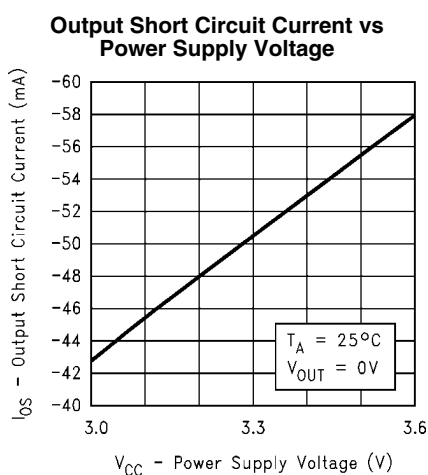
Typical Performance Curves



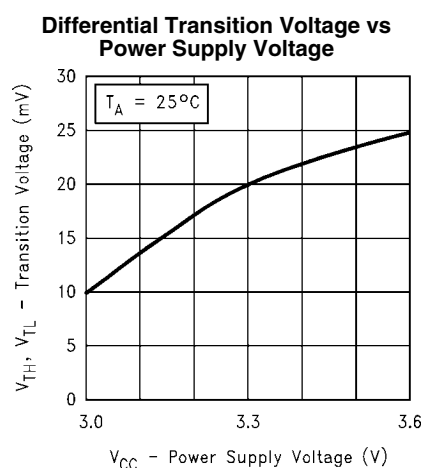
30064107



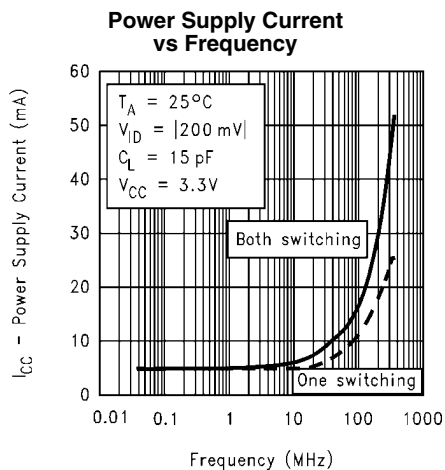
30064108



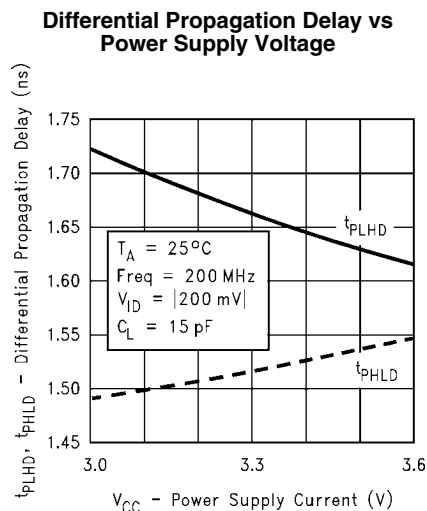
30064109



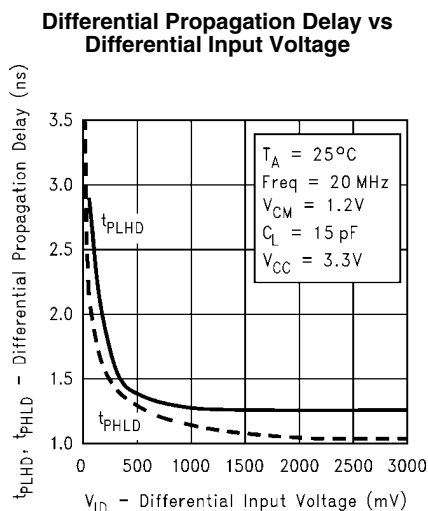
30064110



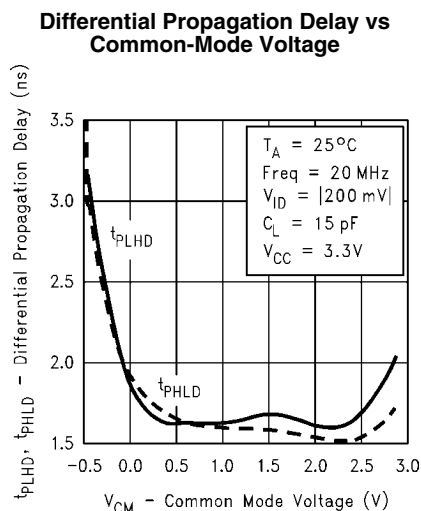
30064111



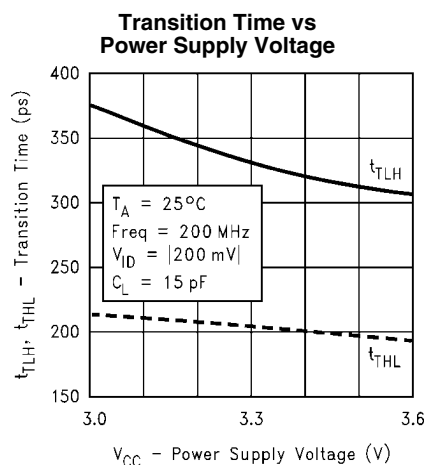
30064113



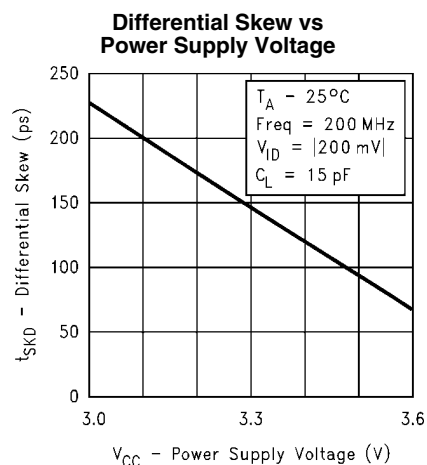
30064117



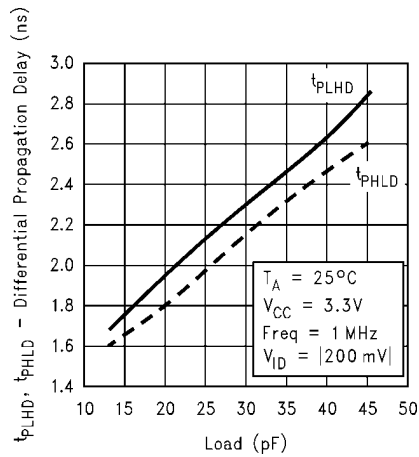
30064118



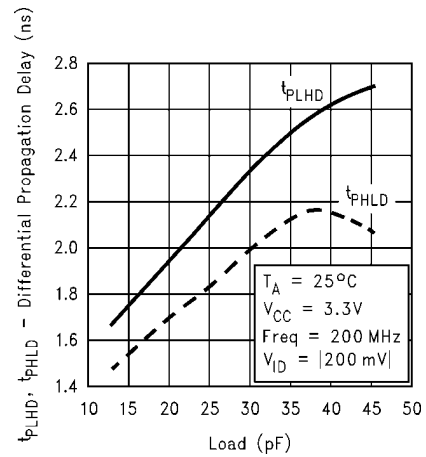
30064119



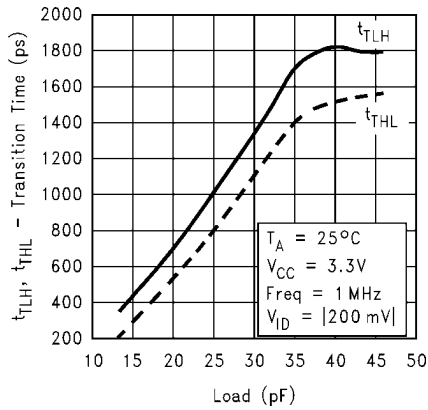
30064115

**Differential Propagation Delay
vs Load**

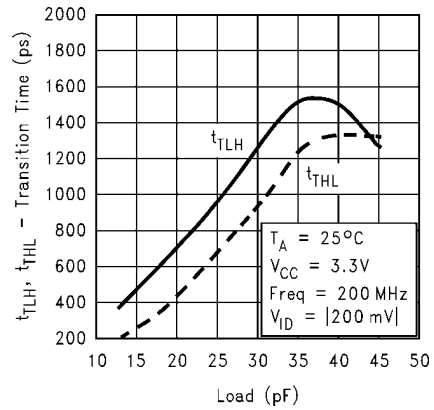
30064121

**Differential Propagation Delay
vs Load**

30064123

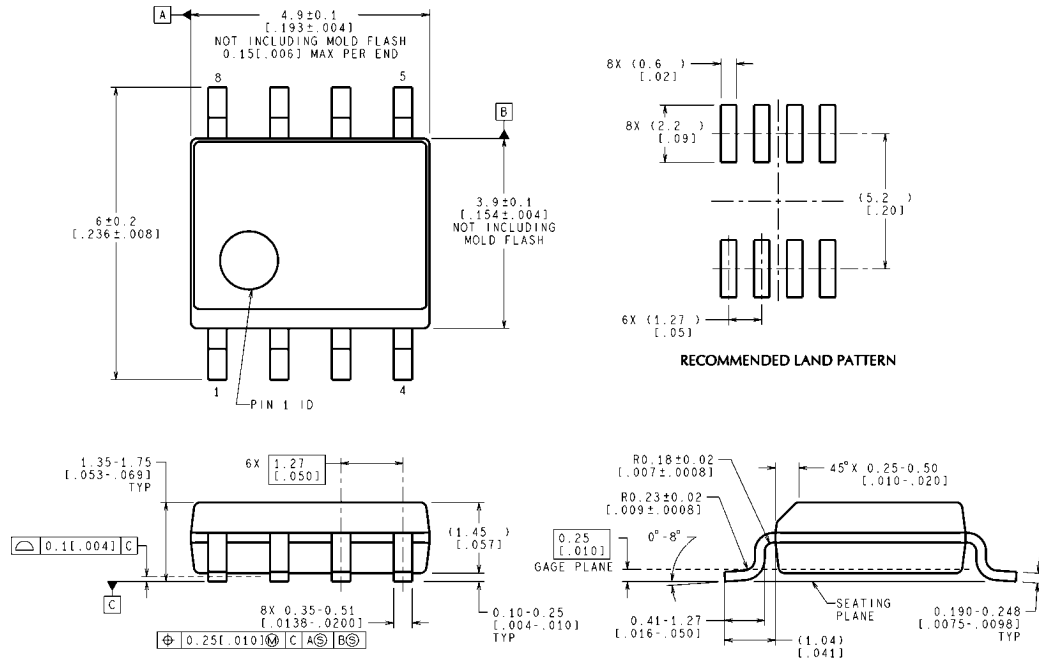
**Transition Time
vs Load**

30064122

**Transition Time
vs Load**

30064124

Physical Dimensions inches (millimeters) unless otherwise noted



CONTROLLING DIMENSION IS MILLIMETER
VALUES IN [] ARE INCHES
DIMENSIONS IN () FOR REFERENCE ONLY

8-Lead (0.150 Wide) Molded Small Outline Package, JEDEC
Order Number DS90LV028AQMA
NS Package Number M08A

M08A (Rev L)

Notes

Notes

For more National Semiconductor product information and proven design tools, visit the following Web sites at:

Products		Design Support	
Amplifiers	www.national.com/amplifiers	WEBENCH	www.national.com/webench
Audio	www.national.com/audio	Analog University	www.national.com/AU
Clock Conditioners	www.national.com/timing	App Notes	www.national.com/appnotes
Data Converters	www.national.com/adac	Distributors	www.national.com/contacts
Displays	www.national.com/displays	Green Compliance	www.national.com/quality/green
Ethernet	www.national.com/ethernet	Packaging	www.national.com/packaging
Interface	www.national.com/interface	Quality and Reliability	www.national.com/quality
LVDS	www.national.com/lvds	Reference Designs	www.national.com/refdesigns
Power Management	www.national.com/power	Feedback	www.national.com/feedback
Switching Regulators	www.national.com/switchers		
LDOs	www.national.com/lldo		
LED Lighting	www.national.com/led		
PowerWise	www.national.com/powerwise		
Serial Digital Interface (SDI)	www.national.com/sdi		
Temperature Sensors	www.national.com/tempsensors		
Wireless (PLL/VCO)	www.national.com/wireless		

THE CONTENTS OF THIS DOCUMENT ARE PROVIDED IN CONNECTION WITH NATIONAL SEMICONDUCTOR CORPORATION ("NATIONAL") PRODUCTS. NATIONAL MAKES NO REPRESENTATIONS OR WARRANTIES WITH RESPECT TO THE ACCURACY OR COMPLETENESS OF THE CONTENTS OF THIS PUBLICATION AND RESERVES THE RIGHT TO MAKE CHANGES TO SPECIFICATIONS AND PRODUCT DESCRIPTIONS AT ANY TIME WITHOUT NOTICE. NO LICENSE, WHETHER EXPRESS, IMPLIED, ARISING BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT.

TESTING AND OTHER QUALITY CONTROLS ARE USED TO THE EXTENT NATIONAL DEEMS NECESSARY TO SUPPORT NATIONAL'S PRODUCT WARRANTY. EXCEPT WHERE MANDATED BY GOVERNMENT REQUIREMENTS, TESTING OF ALL PARAMETERS OF EACH PRODUCT IS NOT NECESSARILY PERFORMED. NATIONAL ASSUMES NO LIABILITY FOR APPLICATIONS ASSISTANCE OR BUYER PRODUCT DESIGN. BUYERS ARE RESPONSIBLE FOR THEIR PRODUCTS AND APPLICATIONS USING NATIONAL COMPONENTS. PRIOR TO USING OR DISTRIBUTING ANY PRODUCTS THAT INCLUDE NATIONAL COMPONENTS, BUYERS SHOULD PROVIDE ADEQUATE DESIGN, TESTING AND OPERATING SAFEGUARDS.

EXCEPT AS PROVIDED IN NATIONAL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, NATIONAL ASSUMES NO LIABILITY WHATSOEVER, AND NATIONAL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY RELATING TO THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS PRIOR WRITTEN APPROVAL OF THE CHIEF EXECUTIVE OFFICER AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

Life support devices or systems are devices which (a) are intended for surgical implant into the body, or (b) support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in a significant injury to the user. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system or to affect its safety or effectiveness.

National Semiconductor and the National Semiconductor logo are registered trademarks of National Semiconductor Corporation. All other brand or product names may be trademarks or registered trademarks of their respective holders.

Copyright© 2008 National Semiconductor Corporation

For the most current product information visit us at www.national.com



**National Semiconductor
Americas Technical
Support Center**
Email: support@nsc.com
Tel: 1-800-272-9959

**National Semiconductor Europe
Technical Support Center**
Email: europe.support@nsc.com
German Tel: +49 (0) 180 5010 771
English Tel: +44 (0) 870 850 4288

**National Semiconductor Asia
Pacific Technical Support Center**
Email: ap.support@nsc.com

**National Semiconductor Japan
Technical Support Center**
Email: jpn.feedback@nsc.com